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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Application Serial No		
Filing Date	App. A. Silver	
Inventor	APK Z = 2002	1/4/01 Ahn et al.
Assignee	R	Micron Technology, Inc.
Group Art Unit	CA CO	2813 E. Kielin
Examiner	VADEMA	E. Kielin
Attorney's Docket NoMI2		
Title: Methods of Forming Assemblies Comprising Silicon-Doped Aluminum Oxide		

RESPONSE TO FEBRUARY 27, 2002 OFFICE ACTION

To:

Assistant Commissioner for Patents

Washington, D.C. 20231

From:

David G. Latwesen (Tel. 509-624-4276; Fax 509-838-3424)

Wells St. John P.S.

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APR 29 2002 TECHNOLOGY CENTER 2800

AMENDMENTS

In the Specification

Please replace the title with:

--Methods of Forming Assemblies Comprising Silicon-Doped Aluminum Oxide--

Please replace the paragraph beginning at line 22 of page 1 with the following clean replacement paragraph in accordance with 37 C.F.R. § 1.121(b)(1)(ii):

--Of the listed high-k materials, aluminum oxide has received significant interest.

Aluminum oxide has been used as a high-k inter-poly dielectric (IPD) for low voltage/high speed flash memories. Specifically, it has been shown that 10 nanometer thick Al₂O₃, with

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